PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
TAIGA MARUKAWA	03/03/2022
GILBERTO LARRACHE-IRIZARRY	03/03/2022
DOUGLAS M. DAFLER	03/04/2022
PATRICK J. ELLISON	03/04/2022
KOSAKU TOMOZAWA	03/10/2022
KEIICHIRO TSUJI	03/08/2022
ANTHONY JOHN LEANZA	03/05/2022
TAKASHI NAKANO	03/07/2022

RECEIVING PARTY DATA

Name:	HONDA MOTOR CO., LTD.
Street Address:	1-1, MINAMI-AOYAMA 2-CHOME
Internal Address:	MINATO-KU
City:	TOKYO
State/Country:	JAPAN
Postal Code:	107-8556

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17696430

CORRESPONDENCE DATA

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 216-566-9700

Email: overberger@rankinhill.com **Correspondent Name:** RANKIN, HILL & CLARK LLP

Address Line 1: 23755 LORAIN ROAD

Address Line 2: SUITE 200

Address Line 4: NORTH OLMSTED, OHIO 44070

ATTORNEY DOCKET NUMBER:	HRA-51993
NAME OF SUBMITTER:	ROBERT A. SIDOTI

507181104 PATENT REEL: 059284 FRAME: 0845

SIGNATURE:	/Robert A. Sidoti/
DATE SIGNED:	03/16/2022
Total Attachments: 10	
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PATENT REEL: 059284 FRAME: 0846

PATENT APPLICATION

Docket No.: HRA-51993

ASSIGNMENT

I/We the undersigned, hereinafter collectively referred to as "Assignor", have made an invention entitled

VEHICLE MOUNTED MODULE SUPPORT SYSTEM

Preferred embodiments of said invention are disclosed in a United States patent application which:

X Is executed concurrently herewith for filing in the United States Patent and Trademark Office and has been assigned Application Serial No. with a filing date of

Was previously filed in the United States Patent and Trademark Office on as Application Serial No.

Is a United States National Application of PCT International Application No. filed

(The undersigned hereby grants to the attorneys of

RANKIN, HILL & CLARK LLP

and American Honda Motor Co., Inc. the power to insert on this assignment any identification that may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document, including but not limited to the application number and filing date, if not already provided in this document.)

WHEREAS, The Assignee, Honda Motor Co., Ltd., having a principal place of business at

1-1, Minami-Aoyama 2-Chome, Minato-ku, Tokyo, 107-8556, Japan

desires to secure the entire right, title, and interest, throughout the world, in, to, and under said invention and the patent rights therefor.

NOW, THEREFORE, be it known that, for valuable consideration, the receipt and sufficiency of which is hereby acknowledged, all right, title, and interest, in the United States and throughout the world, in, to and under said invention and all patents, patent applications, patent rights, and inventor's certificates thereof, therefor, and therein, including without limitation said application for patent in the United States, all divisions and continuations thereof, all patents which may be granted thereon, all reissues and extensions thereof, all right to sue for past infringement thereunder, all patents which may be granted for said invention by states or nations other than the United States, or by other authority, entity, or organization, and all applications therefor, have been and are hereby sold, assigned, transferred, and delivered unto assignee, its successors and assigns; and it is covenanted and agreed by the undersigned, and for executors, administrators, and legal representatives of the undersigned, that at assignee's request any and all applications, affidavits, assignments, and other instruments will be made, executed, and delivered as may be necessary, or desirable to secure for or vest in assignee, its successors or assigns, any invention, right, title, interest, application, patent, patent right or other right or property covered by this assignment, and the United States Commissioner of Patents and Trademarks is hereby requested and authorized to issue any and all United States patents granted on any of said applications to assignee as owner of the entire right, title, and interest in, to, and under the same, and appropriately empowered officials of foreign countries are hereby authorized to issue any letters patent granted on any of said applications to assignee as owner of the entire right, title and interest in, to, and under the same, including the right to claim the benefits of the International Convention for such applications.

ASSIGNMENT HRA-51993

This	assignment	and	agreement	shall	be	binding	upon	Assignor's	heirs	and	legal
repre	esentatives.										

Inventor 1 Name:

Taiga MARUKAWA

Inventor's signature:_/Taiga Marukawa/_ Date:_3/3/2022___

This	assignment	and	agreement	shall	be	binding	upon	Assignor's	heirs	and	legal
repre	esentatives.										

Inventor 2 Name:

Gilberto LARRACHE-IRIZARRY

Inventor's signature: /Gilberto Larrache/ Date: 3/3/2022

ASSIGNMENT HRA-51993

This assignment representatives.	and agreement	shall	be	binding	upon	Assignor's	heirs	and	legal
Inventor 3 Name:									
<u>Douglas M. DAFL</u>	<u>ER</u>								
Inventor's signatu	re: <u>/Douglas Dafle</u>	<u>er/</u>		Date:_	<u>3/4</u>	/2022			

This assignment representatives.	and	agreement	shall	be	binding	upon	Assignor's	heirs	and	lega
Inventor 4 Name:										
Patrick J. ELLISO	<u>N</u>									
Inventor's signatur	e:	/Patrick J E	Ellison	/	Date:	3-	4-2022			

This assignm representative		agreement	shall b	e binding	upon	Assignor's	heirs	and	legal
Inventor 5 Na	me:								
Kosaku TOM(<u>DZAWA</u>								
Inventor's Date:_	03/10/20	signatu 022	re: <u>/K</u>	osaku		Tomo	ozawa/	_	

This assignment representatives.	and	agreement	shall	be	binding	upon	Assignor's	heirs	and	legal
Inventor 6 Name:										
Keiichiro TSUJI										
Inventor's signatur	re:	/Keiichiro Ts	suji/	_	Date:_		_ 03/08/202	2		

This assignment and agreement shall be binding upon Assignor's heirs and legal representatives.

Inventor 7 Name:

Anthony John LEANZA

Inventor's /Anthony John Leanza/ Date:_03/05/2022_

ASSIGNMENT HRA-51993

This assignment representatives.	and	agreement	shall	be	binding	upon	Assignor's	heirs	and	lega
Inventor 8 Name:										
<u>Takashi NAKANO</u>										
Inventor's signatur	.e.	/Takashi N	akano	1		Date.	03/0	7/202	2	

PATENT